

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
03 July 2025 (03.07.2025)



(10) International Publication Number
WO 2025/140916 A1

(51) International Patent Classification:
H03H 3/08 (2006.01) *H03H 3/02* (2006.01)

(21) International Application Number:
PCT/EP2024/087207

(22) International Filing Date:
18 December 2024 (18.12.2024)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2023-221975 27 December 2023 (27.12.2023) JP

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(81) Designated States (*unless otherwise indicated, for every
kind of national protection available*): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG,
KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY,
MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every
kind of regional protection available*): ARIPO (BW, CV,
GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST,
SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ,
RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ,
DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT,
LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE,
SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, KM, ML, MR, NE, SN, TD, TG).

(54) Title: METHOD OF MANUFACTURING ACOUSTIC WAVE DEVICE

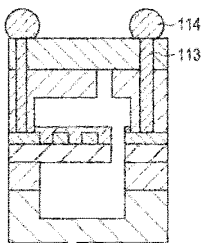
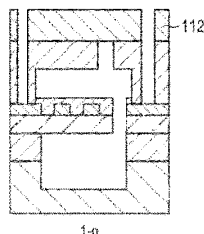


Fig. 1C

(57) Abstract: A method of manufacturing an acoustic wave device according to the present invention comprises the steps of: forming a sacrificial layer by applying a sacrificial liquid to a recessed part of a support substrate having the recessed part on an upper surface of the support substrate; bonding a piezoelectric substrate to an upper side of the support substrate; and heating and removing the sacrificial layer to form an air gap, wherein the sacrificial liquid comprises a polymer and a solvent, and the polymer has a glass transition temperature of from 0 to 180°C.

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Published:

- *with international search report (Art. 21(3))*
- *in black and white; the international application as filed contained color or greyscale and is available for download from PATENTSCOPE*